



INTERNATIONAL MICROELECTRONICS AND PACKAGING SOCIETY

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Micro/Nano-Electronics **Packaging & Assembly**, **Design and Manufacturing Forum** *Conference & 'Interconex' Exhibition*



MiNaPAD forum 2011

Grenoble, France

May 11-12, 2011



« *Bringing closer the design and the semiconductor assembly & packaging communities* »

Announcement & Call for abstracts *now open (deadline is Feb. 1st, 2011)*

Abstracts are being requested on the following topics (min. 250 words):

- Design: CAD and design techniques, IO placement for advanced packaging (fan-out, 3D packaging), design for reliability, IC and package co-design, RF package design, thermal and mechanical predictability (models and simulations)
- Innovative packaging for MEMS and emerging applications: photovoltaic, biosensors, energy scavenging and batteries, high brightness LEDs,...
- System-in-Package for smart systems, telecom, automotive and medical applications: solving test and reliability challenges
- Process, test, reliability, characterization and challenges of advanced packaging platforms: 3D Packaging (with or w/o TSVs), fan-out WLP and embedded IC package.
- Advanced interconnections: flip-chip for high IO count devices and sub 45nm CMOS, new flip-chip and WLP metallurgies, bumping techniques
- A poster session will address all of the above topics. At the discretion of the program committee, submitted abstracts may be considered for poster presentation

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